

#### ThinFlex Corporation

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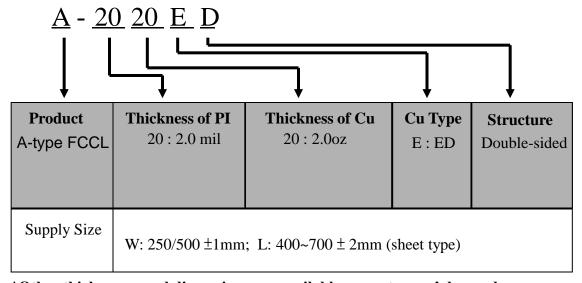
# ThinFlex-A, A-2020ED Adhesiveless Double Sided Copper Clad Laminate (Halogen Free)

ThinFlex-A, A-2020ED is an adhesiveless double sided (D/S) metal clad polyimide film, furnished in the form of roll laminate with ED copper on both sides. ThinFlex-A, A-2020ED adhesiveless D/S composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, and high reliability.

### 1. Product Characteristics:

- \* Excellent dimensional stability
- \* Excellent flexibility
- \* Finer line etch ability
- \* Low moisture absorption
- \* Excellent flammability (Flame class UL 94V-0; UL File No. E219724)
- \* Excellent chemical resistance
- \* Excellent thermal, mechanical, and electrical properties

## 2. Specifications:



<sup>\*</sup>Other thicknesses and dimensions are available on customers' demand.

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# 3. Construction:

Copper foil
Polyimide film
Copper foil

# 4. Properties:

| Test item                             | Unit             | A-2020ED          | Test Method  |
|---------------------------------------|------------------|-------------------|--|
| Peel Strength                         |                  |                   |  |
| As Received                           | Kgf/cm           | $\geqq$ 2.0       | IPC-TM650 2.4.9  |
| Solder Float                          | Kgf/cm           | $\geqq$ 2.0       | IPC-TM650 2.4.9  |
| After Temp. Cycling                   | Kgf/cm           | $\geq 2.0$        | IPC-TM650 2.4.9  |
| Chemical Resistance                   | Kgf/cm           | $\geqq$ 2.0       | IPC-TM650 2.3.2  |
| Tensile Strength (Base Film)          | kg/mm²           | ≧28               | IPC-TM-650 2.4.19                                      |
| Elongation (Base Film)                | %                | ≧50               | IPC-TM-650 2.4.19                                      |
| Tensile Modulus (Base Film)           | kg/mm²           | ≧550              | ASTM D882  |
| Initial Tear Strength (Base Film)     | g                | ≧2100             | IPC-TM-650 2.4.16                                      |
| Propagation Tear Strength (Base Film) | g                | ≧22               | IPC-TM-650 2.4.17.1                                    |
| Flexural Endurance, MIT M.D. T.D.     | Cycles<br>Cycles | NA<br>NA          | JIS-C 6471, 0.8mmR, 0.5kg<br>JIS-C 6471, 0.8mmR, 0.5kg |
| Electrical Properties                 | .,               | INA               | ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,                |
| Surface Resistance                    | Ω                | ~10 <sup>11</sup> | IPC-TM650 2.5.17                                       |
| Volume Resistance                     | Ω-cm             | ~1012             | IPC-TM650 2.5.17                                       |
| Insulation Resistance                 | Ω                | ~109              | IPC-TM650 2.6.3.2                                      |
| Dielectric Strength                   | kV/mil           | 6.9               | ASTM-D149  |
| Dielectric Constant                   | -                | 3.3               | IPC-TM650 2.5.5.3                                      |
| Dissipation factor                    | -                | 0.002             | IPC-TM650 2.5.5.3                                      |
| Physical and Thermal Properties       | 0/               | 0.4.0.4           | IDO TMOSO O O AO                                       |
| M.D. Dimensional Stability T.D.       | %<br>%           | -0.1~0.1          | IPC-TM650 2.2.4C                                       |
| CTE                                   | %<br>ppm/°C      | -0.1~0.1<br>19.3  | IPC-TM650 2.2.4C<br>ThinFlex                           |
| $T_{\alpha}$                          | °C               | 350               | ThinFlex   |
| Solder Float 10sec at 288°C (550°F)   | -                | Pass              | IPC-TM650 2.4.13                                       |
| Moisture Absorption Test              | %                | 1.1               | IPC-TM650 2.6.2  |
| Chemical Resistance-single            | -                | Pass              | IPC-TM650 2.3.2  |
| Thickness tolerance                   | um               | 190±10%           | ThinFlex   |
| UL Flame Class                        | -                | V-0               | UL94   |

<sup>\*</sup> Above data are typical values, and are not guaranteed values.

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## 5. Storage:

ThinFlex-A, A-2020ED will meet its shelf-life for at least 12 months after arrival at the user's factory when stored in the original packaging at temperatures of below 25°C and below 70% humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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